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AMENDMENTS TO THE ABSTRACT:

The invention provides a bonding structure with compliant bumps, and also includes a stopper structure and a protection layer. Compliant bumps include at least a polymer bump, a metal layer and a surface conductive layer. Both the stopper structure and protection layer are formed with polymer bumps and metal layer. Compliant bumps provide bonding pad and conductive channel. Stoppers are used to prevent compliant bumps from crushing for overpressure in bonding process. The protection layer provides functions of grounding and shielding. The stoppers can be outside or connected with the compliant bumps. The protection layer has thickness smaller than is lower than the stopper structure and compliant bumps. It can be separated or connected with stoppers.